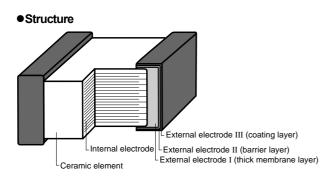
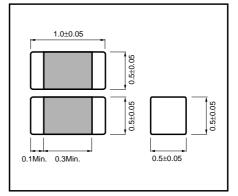
Multi-layer ceramic chip capacitors MCH15 (1005 (0402) size, chip capacitor)

Features

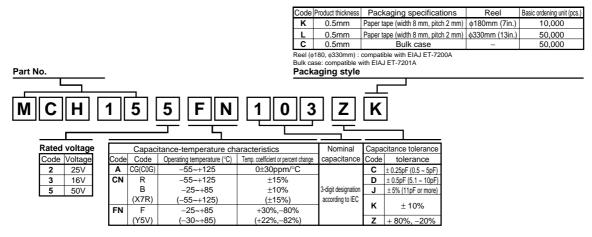
- 1) Small size (1.0 x 0.5 x 0.5 mm) makes it perfect for lightweight portable devices.
- Comes packed either in tape to enable automatic mounting or in bulk cases.
- Precise uniformity of shape and dimensions facilitates highly efficient automatic mounting.
- Barrier layer and end terminations to improve solderability.



• External dimensions (Units : mm)



Product designation





Ceramic capacitors

Capacitance range

For thermal compensation

Part n	MCH15	
Capacitance (pF)	Temperature characteristics	A (CG) (C0G)
Capacitance (pr)	Rated voltage (V) Tolerance	50V
0.5 0.75 1		
1.1 1.2 1.3		
1.5 1.6 1.8		
2 2.2 2.4	C (±0.25pF)	
2.7 3 3.3		
3.6 3.9 4		
4.3 4.7 5		
5.1 5.6 6		
6.2 6.8 7	D (± 0.5pF)	
7.5 8 8.2	_ (,	
9 9.1 10		
11 12 13		
15 16 18		
20 22 24	J (±5%)	
27 30 33		
36 39 43		

	Part number MCH15				
Capacitance (pF)	Temperature characteristics	(CG) (C0G)			
Capacitance (pr)	Rated voltage (V) Tolerance	50V			
47					
51					
56					
62					
68					
75					
82					
91 100					
110					
120					
130					
150	J (± 5%)				
160					
180					
200					
220					
240					
270					
300					
330					
360					
390 430					
430					
470 510					
560					

 $\begin{tabular}{|c|c|} \hline & \hline \\ Product thickness (mm) 0.5 \pm 0.05 \end{tabular}$



High dielectric constant

Part nu	imber			MCH15		
	Temperature characteristics	CN (R) (B) (X7R)		FN (F) (Y5V)		
Capacitance (pF)	Rated voltage (V)	50V	16V	50V	25V	16V
	Tolerance	K (±	10%)	Z (+80, -20%)		
220						
270 330						
390						
470 560						
680						
820						
1,000						
1,200 1,500						
1,800						
2,200						
2,700 3,300						
3,900						
4,700						
5,600						
6,800 8,200						
10,000 (0.01µF)						
12,000						
15,000 18,000						
22,000						
27,000						
33,000						
39,000 47,000						
56,000						
68,000						
82,000 100,000 (0.1μF)						
120,000						
150,000						
180,000						
220,000 270,000						
330,000						
390,000						
470,000 560,000						
000,000						

Product thickness (mm) 0.5 ± 0.05



Characteristics

Class 1 (For thermal compensation)

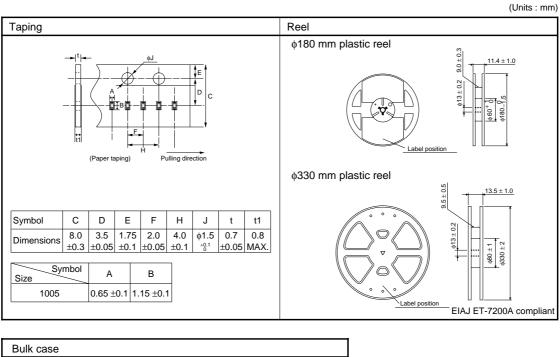
Temperature characteristics		A (CG) (C0G)	Test methods/conditions (based on JIS C 5102)	
Operating temperature		–55°C ~ 125°C		
Nominal capacitance (C)		Must be within the specified tolerance range.	Based on paragraph 7.8 and paragraph 9 Measured at room temperature and standard humidity,	
Dissipation factor ($tan\delta$)		100/(400+20C)% or less: Less than 30 pF 0.1% or less : 30 pF or larger	1000pF or less Measurement frequency : 1 ± 0.1MHz Measurement voltage : 1 ± 0.1Vrms. Over 1000pF Measurement frequency : 1 ± 0.1KHz Measurement voltage : 1 ± 0.1Vrms.	
Insulation resistance (IR)		10,000M or 500M $\Omega \cdot \mu \text{F},$ whichever is smaller	Based on paragraph 7.6 Measurement is made after rated voltage is applied for $60\pm5s.$	
Withstanding voltage		The insulation must not be damaged.	Based on paragraph 7.1 Apply 300% of the rated voltage for 1 to 5s then measure.	
Temperature c	haracteristics	Within 0 \pm 30ppm/°C	The temperature coefficients in table 12, paragraph 7.12 are calculated at 20°C and high temperature.	
Terminal adhe	rence	No detachment or signs of detachment.	Based on paragraph 8.11. 2. Apply 5N for 10 ± 1s in the direction indicated by the arrow.	
	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner	
Resistance to vibration	Rate of capacitance change	Must be within initial tolerance.	shown on the right, subjected to vibration	
	Dissipation factor (tan \delta)	Must satisfy initial specified value.	24 ± 2 hrs. later. Board	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13 Soldering temperature: 235 ± 5°C Soldering time : 2 ± 0.5s	
	Appearance	There must be no mechanical damage.		
	Rate of capacitance change	\pm 2.5% or \pm 0.25 pF, whichever is larger.	Based on paragraph 8.14.	
Resistance to soldering	Dissipation factor (tan \delta)	Must satisfy initial specified value.	Soldering temperature: 260 ± 5°C	
heat	Insulation resistance	10,000M\Omega or 500M\Omega $\cdot\mu\text{F},$ whichever is smaller	Soldering time $:5 \pm 0.5s$ Preheating $:150 \pm 10^{\circ}C$ for 1 to 2 min.	
	Withstanding voltage	The insulation must not be damaged.		
	Appearance	There must be no mechanical damage.		
	Rate of capacitance change	\pm 2.5% or \pm 0.25 pF, whichever is larger.	Based on paragraph 9.3	
Temperature cycling	Dissipation factor (tan b)	Must satisfy initial specified value.	Number of cycles : 5	
	Insulation resistance	10,000M\Omega or 500M\Omega $\cdot\mu\text{F},$ whichever is smaller	Capacitance measured after 24 \pm 2 hrs.	
	Appearance	There must be no mechanical damage.	Based on paragraph 9.9	
Humidity load test	Rate of capacitance change	\pm 7.5% or \pm 0.75 pF, whichever is larger.	Test temperature : 40 ± 2°C Relative humidity: 90% to 95%	
	Dissipation factor (tan)	0.5% or less	Applied voltage : rated voltage	
	Insulation resistance	500M Ω or 25M $\Omega\cdot\mu F,$ whichever is smaller	Test time \pm : 500 to 524 hrs. Capacitance measured after 24 \pm 2 hrs.	
- High-	Appearance	There must be no mechanical damage.	Based on paragraph 9.10	
	Rate of capacitance change	\pm 3.0% or \pm 0.3 pF, whichever is larger.	Test temperature : Max. operating temp.	
temperature load test	Dissipation factor (tan)	0.3% or less	Applied voltage : rated voltage × 200% Test time : 1,000 to 1,048 hrs.	
	Insulation resistance	1,000M\Omega or 50M $\Omega \cdot \mu F$, whichever is smaller	Capacitance measured after 24 ± 2 hrs.	

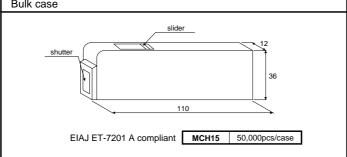


	lectric constant)				
Temperature characteristics		CN (R) (B) (X7R)	FN (F) (Y5V)	Test methods/conditions (based on JIS C 5102)	
Item					
Operating temperature		−55°C ~ +125°C	−30°C ~ +85°C		
Nominal capacitance (C)		Must be within the spe	cified tolerance range.	Based on paragraph 7.8 Measured at room temperature and standard humidi	
Dissipation factor (tanδ)		2.5% or less (when rated voltage is 16V: 3.5% or less)	5.0% or less (when rated voltage is 16V: 7.5% or less)	Measurement frequency: 1 ± 0.1 kHz Measurement voltage : 1.0 ± 0.2 Vrms.	
Insulation resistance (IR)		10,000M\Omega or 500MΩ · μ F, whichever is smaller		Based on paragraph 7.6 Measurement is made after rated voltage is applied for $60 \pm 5s$.	
Withstanding voltage		The insulation must not be damaged.		Based on paragraph 7.1 Apply 250% of the rated voltage for 1 to 5s then measu	
Temperature cl	haracteristics	Within \pm 15%	+ 22, + 82%	The temperature coefficients in paragraph 7.12, table 8, condition B, are based on measurements carried out at 20°C, with no voltage applied.	
Terminal adher	ence	No detachment or signs of detachment		Based on paragraph 8. 11. 2. Apply 5N for 10 ± 1s in the direction indicated by the arrow.	
	Appearance	There must be no n	nechanical damage.	Chip is mounted to a board in the	
Resistance to vibration	Rate of capacitance change	e Must be within initial tolerance.		manner shown on the right, subjected to vibration (type A in paragraph 8.2),	
	Dissipation factor (tan δ)	Must satisfy initial specified value.		and measured 48 ± 4 hrs. later. Board	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.		$\begin{array}{rl} \text{Based on paragraph 8. 13} \\ & \text{Soldering temperature}: 235 \ \pm 5^\circ\text{C} \\ & \text{Soldering time} & : 2 \pm 0.5 s \end{array}$	
	Appearance	There must be no mechanical damage.			
[Rate of capacitance change	Within ± 5.0%	Within $\pm 20.0\%$	Based on paragraph 8. 14.	
Resistance to soldering	Dissipation factor (tan δ)	Must satisfy initial specified value.		Soldering temperature : $260 \pm 5^{\circ}C$	
heat	Insulation resistance	10,000M\Omega or 500M\Omega $\cdot\mu F,$ whichever is smaller		Soldering time: $5 \pm 0.5s$ Preheating: $150 \pm 10^{\circ}C$ for 1 to 2 min.	
	Withstanding voltage	The insulation must not be damaged.			
	Appearance	There must be no mechanical damage.			
Temperature	Rate of capacitance change	Within ± 7.5%	Within ± 20.0%	Based on paragraph 9.3 Number of cycles : 5	
cycling	Dissipation factor (tan δ)	Must satisfy initial specified value.		Capacitance measured after 48 ± 4 hr	
	Insulation resistance	10,000M\Omega or 500MΩ $\cdot\mu\text{F},$ whichever is smaller			
Humidity load test	Appearance	There must be no mechanical damage.		Based on paragraph 9.9	
	Rate of capacitance change	± 12.5% or less	Within \pm 30.0%	Test temperature: 40 ± 2°C	
	Dissipation factor $(tan \delta)$	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)	Relative humidity: 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs	
	Insulation resistance	500M\Omega or 25M $\Omega \cdot \mu F$, whichever is smaller		Capacitance measured after 48 ± 4 hr	
High- temperature load test	Appearance	There must be no mechanical damage.			
	Rate of capacitance change	Within ± 10.0%	Within ± 30.0%	Based on paragraph 9.10	
	Dissipation factor $(tan \delta)$	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)	Test temperature : Max. operating tem Applied voltage : rated voltage × 200 Test time : 1,000 to 1,048 hrs.	
	Insulation resistance	1,000MΩ or 50MΩ · μ	F, whichever is smaller	Capacitance measured after 48 \pm 4 hr	



Packaging specifications

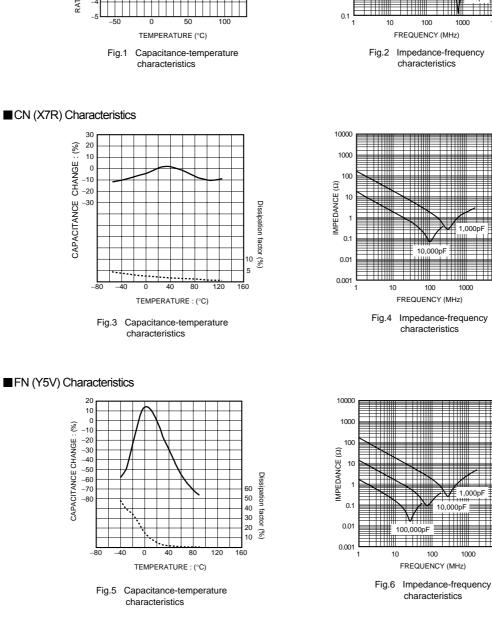






ROHM

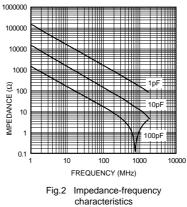
*The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.



Ceramic capacitors

•Electrical characteristics

■A (C0G) Characteristics (%) RATE OF CAPACITANCE CHANGE

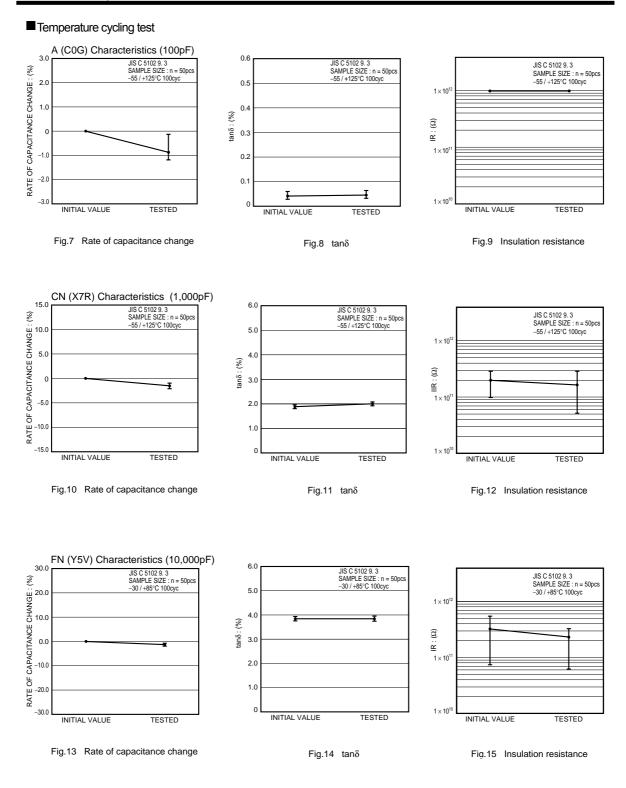


10000

10000

MCH15

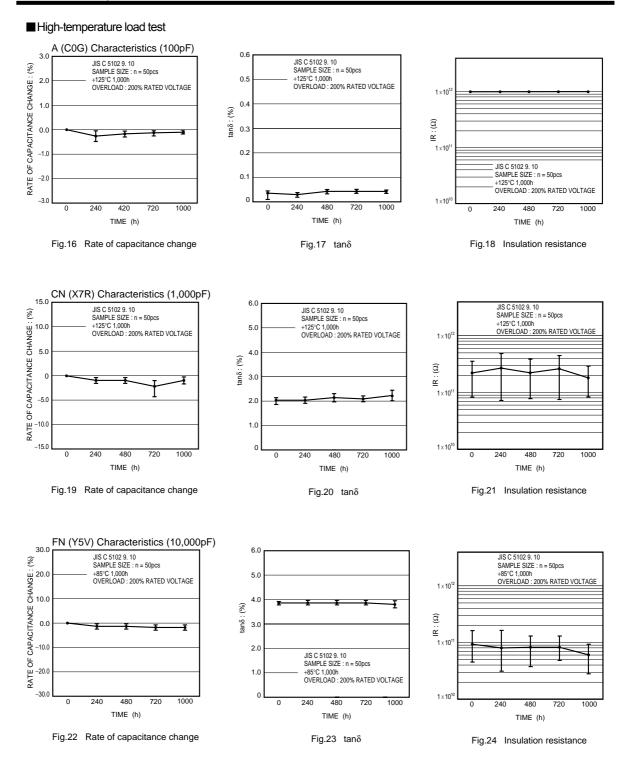
Ceramic capacitors



*The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

ROHM

Ceramic capacitors



*The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

ROHM

Ceramic capacitors

